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DISMANTLING AND TREATMENT INFORMATION

Location Sensor (LAP) Product

Conforms to **Waste electrical and electronic equipment (WEEE)**
2002/96/EC

Category 3 product according Annex IA

Date: 10 October 2011

Zebra Technologies
2940 North 1st Street
San Jose, CA 95134
www.zebra.com

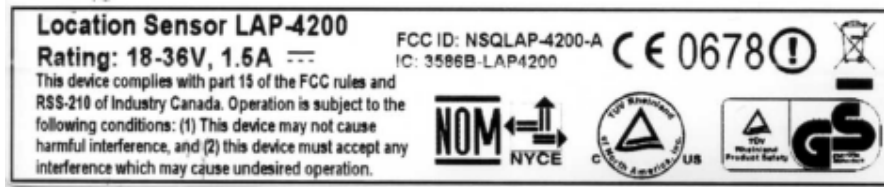
Reuse and treatment information

Material	Weight [g]	Weight [%]	Important Information
Waste Disposal (WD)			
Ceramic	0	0	
Subtotal	0	0	
Recovery Operations (RO)			
Leather	0	0	
Rubber / elastomere	1	0	
Sealant compound	0	0	
Wood	0	0	
Subtotal	1	0	
Aluminium alloy cast			
Aluminium alloy cast	4721	86	
Aluminium alloy wrought	0	0	
Battery	0	0	
Cable	0	0	
Cable with plug	163	3	Remove cables with plugs (8)
Carton	0	0	
Copper	0	0	
Copper Alloy	0	0	
Gas	0	0	
Glass Optical	0	0	
Iron	0	0	
Liquid	0	0	
Magnesium alloy	0	0	
Magnetic material	0	0	
Metal nonferrous	0	0	
Paper	0	0	
Plastic	341	6	
Plug	0	0	
Printed circuit board	247	5	Remove printed circuit boards (2)
Sintered material	0	0	
Steel	0	0	
Steel stainless	0	0	
Textile material	0	0	
Subtotal	5472	100	
Re-Use (RU)			
Subtotal	0	0	
Total weight	5473 g	100%	

Product identification and selective treatment information



26.7 cm x 29.2 cm x 8.2 cm



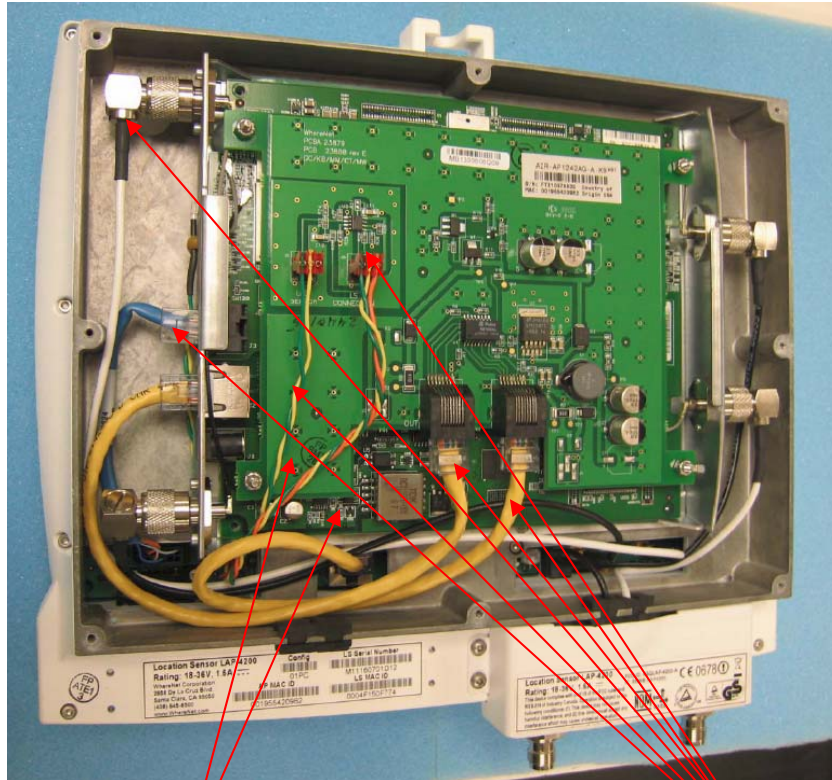
Product Description:

The WhereLAN Locating Access Point (LAP) is a core component of Zebra's Real Time Locating System (RTLS). This unit provides a robust infrastructure for ANSI 371.1 RTLS and data telemetry reception along with a choice of 802.11b Wi-Fi compliant communications.

The cast aluminum body complies with IP 54, as well as NEMA 3 and NEMA 12 environmental standards. These devices can be used indoors or outdoors.

Dismantling Instructions

- A) Remove back cover held on by 8 screws.
- B) Remove printed circuit boards held on by screws.
- C) Remove cables from printed circuit board by either cutting or disconnecting.



Printed Circuit Boards

Cable Assembly